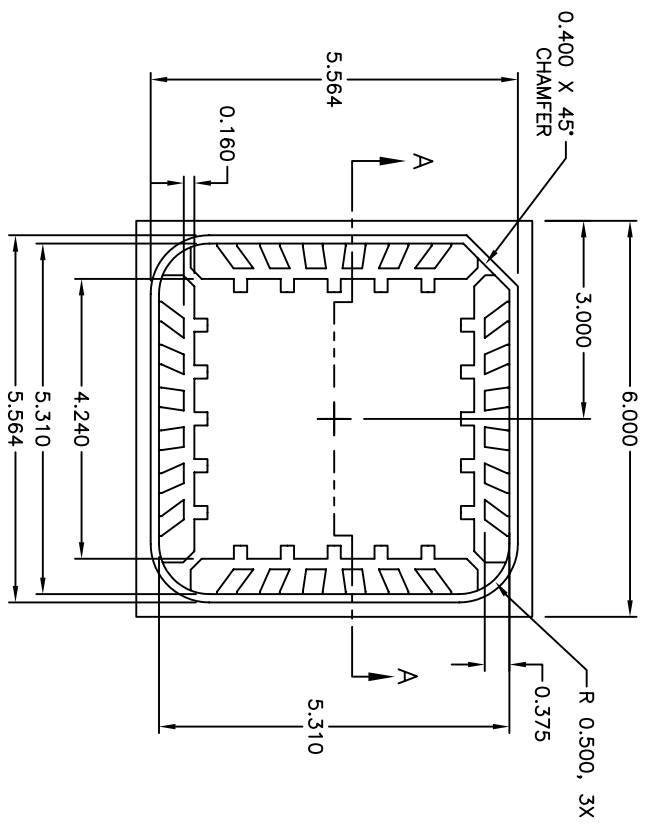


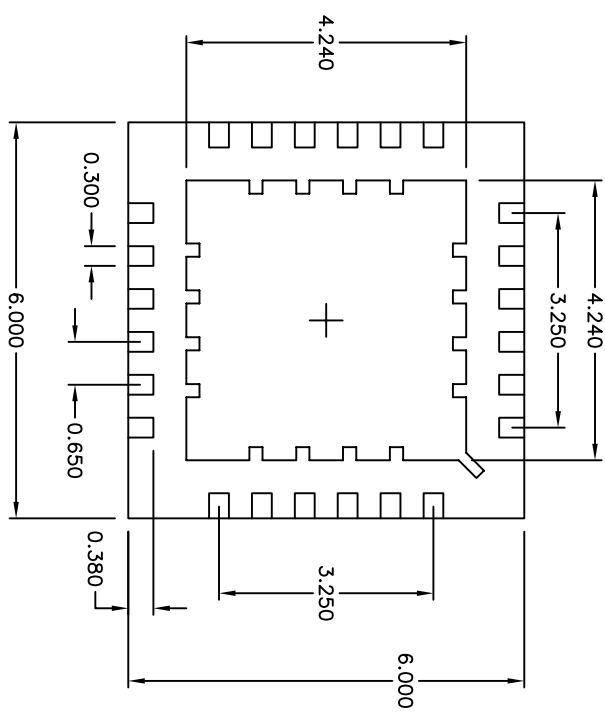
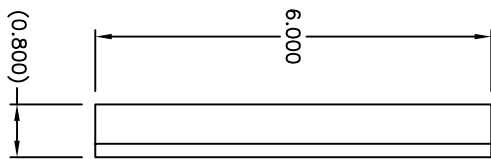
2

1

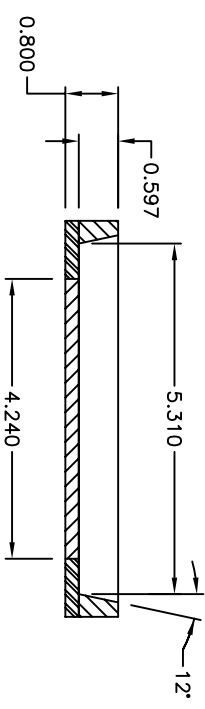
REVISIONS		
EON NO.	DATE	DESCRIPTION
10593	1/19/06	PRODUCTION RELEASE
		APPROVED
		D.BENANDO



TOP VIEW



BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FINISH: FULL GOLD PLATE.
 3. LEAD THICKNESS: 0.2030 ± 0.0076.
 4. DIE PAD: 4.240mm X 4.240mm.
 5. JEDEC OUTLINE: MO-220 (VJJC-1).



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
TOLERANCES ARE: X.XXX ± 0.015 X.XXXX ± 0.005
ANGLES: ± 1°
DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	1/19/06
APP BY	P. FLASKERUD	DATE	1/19/06
CUSTOMER	---		

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24 Lead 6mm x 6mm
MLP Open-Pak

SIZE	PART NO.	REV
A	MLP6X6-24-OP-01	1
SCALE	NONE	
FILE	MLP6X6-24-OP-01-R1.DWG	
SHEET	1 OF 1	

2

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